

NOTE:

1.MATERIAL SPECIFICATION:

- 1-1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
- 1-2.CONTACTS:COPPER ALLOY
- 1-3.MID PLATE: STAINLESS STEEL
- 1-4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

- Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
CONTACT FUNCTIONAL AREA PLATED: Au G/F
CONTACT SOLDER AREA PLATED: Au G/F.

3.MECHANICAL PERFORMANCE,

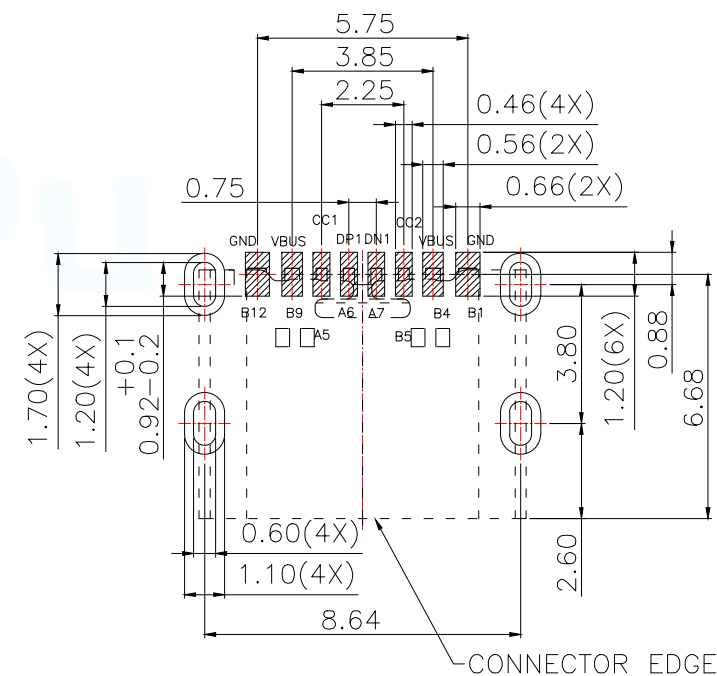
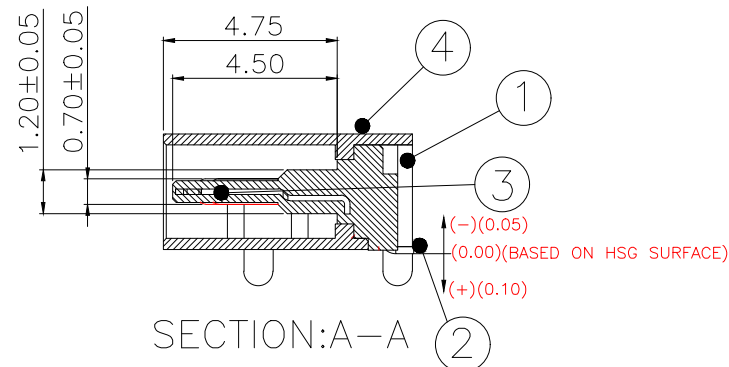
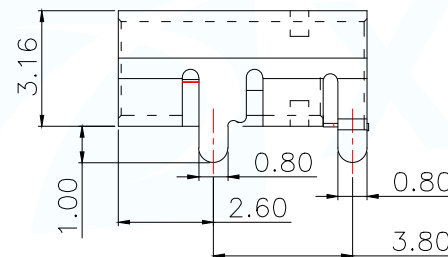
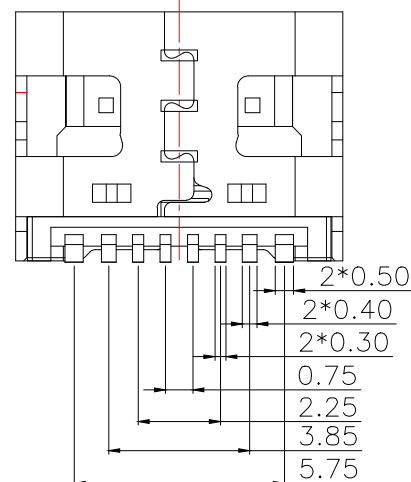
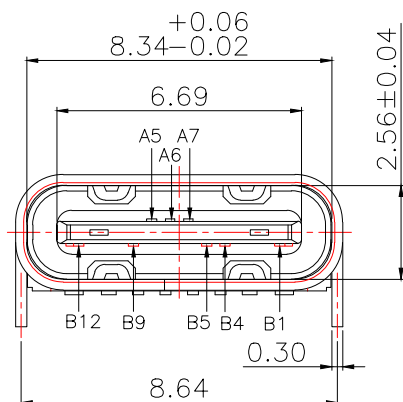
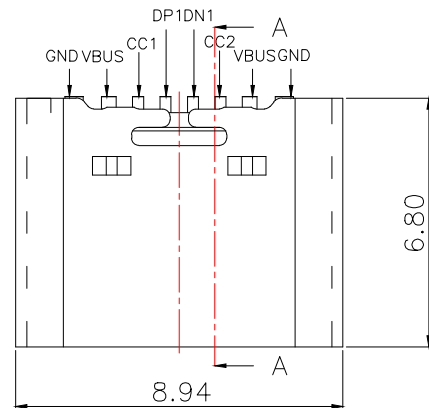
- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,

- 4-1. CURRENT RATING:3.0A
VOLTAGE RATING:5.0V
 - 4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 - 4-3.INSULATION RESISTANCE: 100MΩ MIN
 - 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
- 5.ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25℃~+85℃.
- 6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260℃.

USB TYPE-C PIN ASSIGNMENTS

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
\	\	\	\	CC1	DP1	DN1	\	\	\	\	\
GND	\	\	VBUS	\	\	\	CC2	VBUS	\	\	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1



PCB参考图

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			
DECIMALS:	ANGLES:	TITLE: TYPE-C 8P零铜片 四脚插板1.0无弹	
X.:±0.50	±1°	PAR	TYPE-C-802-WSRL680
X.X:±0.30		DWN	Lucas
X.XX:±0.20		CHKD	Ethan
		APVD	Jacob
		SCALE:1:1	UNIT:MM
		SIZE:A4	SHEET:1F1
		CUSTOMER COPY	REV:A